

Global 3D TSV Devices Market 2016 Share, Trend, Segmentation and Forecast to 2020

3D TSV Devices Market 2016 Global Trends, Market Share, Industry Size, Growth, Opportunities, and Market Forecast to 2020

PUNE, INDIA, July 11, 2016 /EINPresswire.com/ -- The global market for 3D TSV Devices is anticipated to reach XX billion by 2020, driven by the rising drift to decrease package size of parts in electronic systems.

Three-Dimensional (3D) Through-Silicon-Via (TSV) technology is progressively getting importance as a highly-sophisticated semiconductor packaging model that significantly ameliorates chip performance and functionality. 3D TSV devices have stacked silicon wafers that are interconnected perpendicularly by using TSVs. They offer various advantages in wafer/chip assembly, which comprises superior performance as compared to conventional techniques, decrease in packaging dimension, diverse amalgamation, and greater performance. Driven by the rising demand for novel, high-performance chip architectures featuring advantages such as greater performance, power utilization and form factor features, 3D TSV technology is making healthy progress in the semiconductor industry. The development in the 3D TSV advanced wafer packaging technology market is presently fuelled by factors such as strong outlook for the Information & Communication Technologies (ICT) sector, extension in communication services provider (CSP) operations, intensified activity in corporate data centres, and increasing propagation of cloud computing services.



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Future development in the market will be mainly driven by major opportunities in application areas such as MEMS, imaging & optoelectronics, memory, CMOS image sensors, and advanced LED packaging among others. Leveraging its capability to deliver advanced integrated chip models with lesser footprint and decreased capacitance, 3D TSV technology is progressively being used in improving the memory, logic functions of electronics, CMOS and non-memory such as tablet PCs, smart phones, and televisions among others. The propagation of 3D TSV in the DRAM memory vertical with pioneering technology platforms such as Wide I/O, High Bandwidth Memory (HBM) and Hybrid Memory Cube (HMC) is also contributing to the market growth.

Major players in the market include Sony Corporation, Taiwan Semiconductor Manufacturing Company Limited (TSMC), Teledyne DALSA Inc., Amkor Technology Inc., Invensas Corporation,

Samsung Electronics Co. Ltd., STATS ChipPAC Ltd., Micron Technology Inc., Iwate Toshiba Electronics Co. Ltd., SK Hynix Inc., Tezzaron Semiconductor Corp., United Microelectronics Corporation (UMC), GLOBALFOUNDRIES, and Xilinx Inc., among others.

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